

EVVOSEMI[®]

THINK CHANGE DO



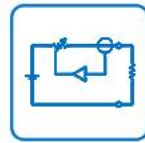
ESD



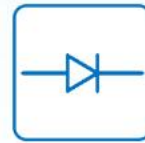
TVS



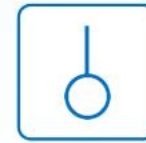
MOS



LDO



Diode



Sensor



DC-DC

Product Specification

▶ Domestic	Part Number	FS8205A
▶ Overseas	Part Number	FS8205A
▶ Equivalent	Part Number	FS8205A

EV is the abbreviation of name EVVO

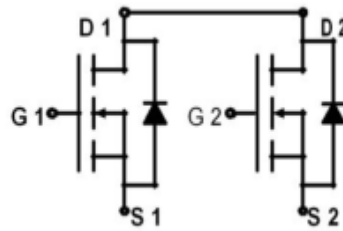
20V N+N-Channel Enhancement Mode MOSFET

Description

The FS8205A uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

Application

- Battery protection
- Load switch
- Powermanagement



Schematic diagram

General Features

- $V_{DS} = 20V, I_D = 6A$
- $R_{DS(ON)} < 22.5.m\Omega @ V_{GS}=4.5V$
- $R_{DS(ON)} < 27.m\Omega @ V_{GS}=2.5V$

SOT23-6L Pin Configuration

Package Marking and Ordering Information

Product ID	Package	Marking	QTY(PCS)	Packing method
FS8205A	SOT23-6L	8205A	3000	Reel

Absolute Maximum Ratings@ $T_j=25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D@T_A=25^\circ C$	Drain Current, $V_{GS} @ 4.5V^3$	6	A
$I_D@T_A=70^\circ C$	Drain Current, $V_{GS} @ 4.5V^3$	4.8	A
IDM	Pulsed Drain Current ¹	26	A
$P_D@T_A=25^\circ C$	Total Power Dissipation	2	W
	Linear Derating Factor	0.016	W/°C
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction-ambient ³	62.5	°C/W

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Electrical Characteristics@ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=4.5V, I_D=6A$	-	20.5	27	$m\Omega$
		$V_{GS}=2.5V, I_D=4A$	-	27	37	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	-	0.75	1.2	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=6A$	-	6	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=20V, V_{GS}=0V$	-	-	25	μA
	Drain-Source Leakage Current ($T_j=70^{\circ}\text{C}$)	$V_{DS}=20V, V_{GS}=0V$	-	-	250	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
Q_g	Total Gate Charge ²	$I_D=6A$	-	11	17.6	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=16V$	-	1.1	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	4.1	-	nC
$t_{d(on)}$	Turn-on Delay Time ²	$V_{DS}=10V$	-	4.2	-	ns
t_r	Rise Time	$I_D=1A$	-	9	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega, V_{GS}=10V$	-	23	-	ns
t_f	Fall Time	$R_D=10\Omega$	-	3.5	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	570	910	pF
C_{oss}	Output Capacitance	$V_{DS}=20V$	-	90	-	pF
C_{rss}	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	85	-	pF
R_g	Gate Resistance	$f=1.0\text{MHz}$	-	1.6	2.4	Ω
V_{SD}	Forward On Voltage ²	$I_S=1.7A, V_{GS}=0V$	-	-	1.2	V
t_{rr}	Reverse Recovery Time ²	$I_S=6A, V_{GS}=0V, dI/dt=100A/\mu s$	-	21	-	ns
Q_{rr}	Reverse Recovery Charge		-	14	-	nC

1. Pulse width limited by Max. junction temperature.

2. Pulse test

3. Surface mounted on 1 in² copper pad of FR4 board, $t \leq 10\text{sec}$; 135°C/W when mounted on Min. copper pad.

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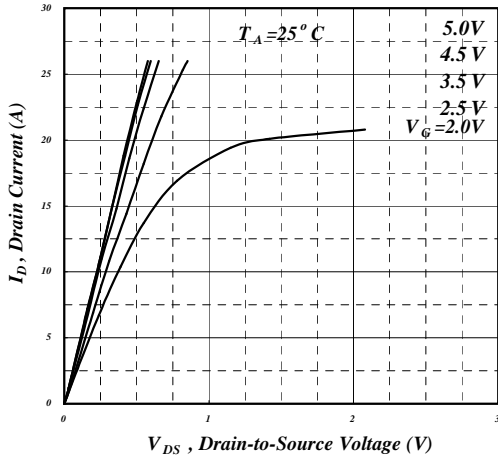


Fig 1. Typical Output Characteristics

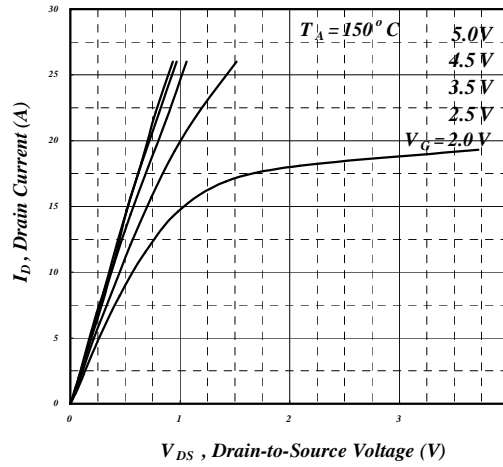


Fig 2. Typical Output Characteristics

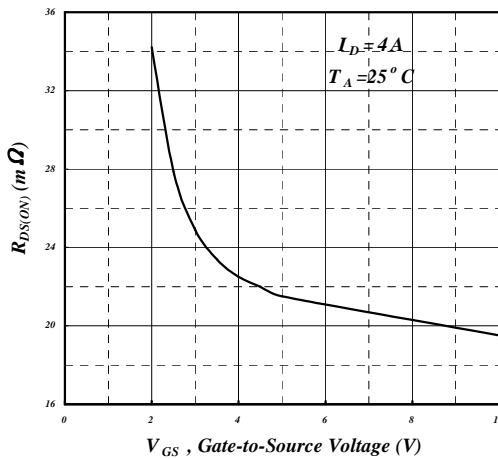


Fig 3. On-Resistance v.s. Gate Voltage

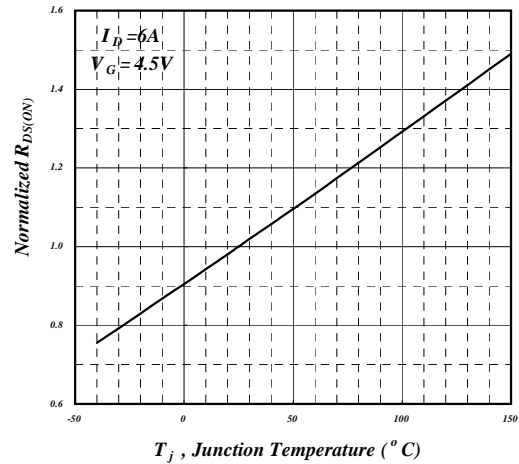


Fig 4. Normalized On-Resistance v.s. Temperature

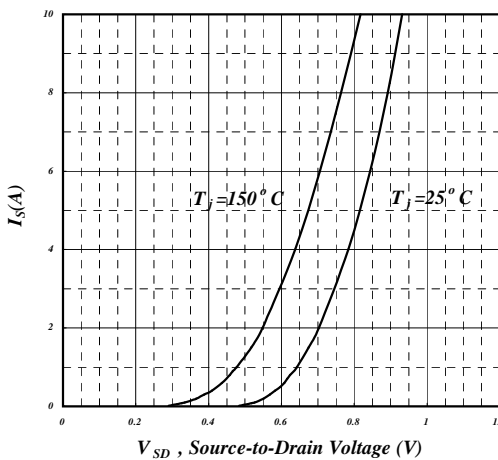


Fig 5. Forward Characteristic of Reverse Diode

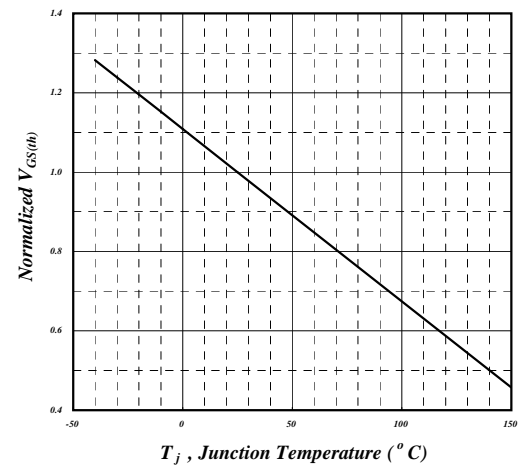


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

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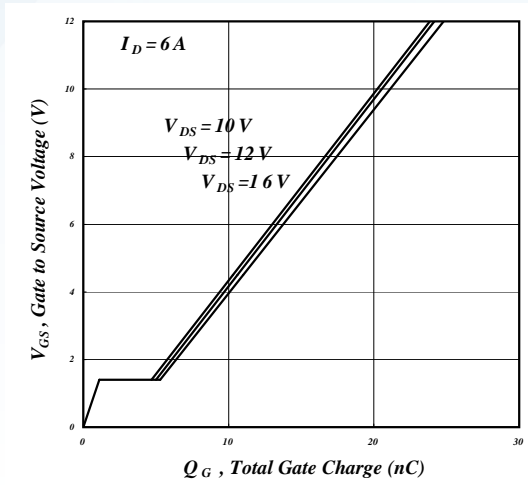


Fig 7. Gate Charge Characteristics

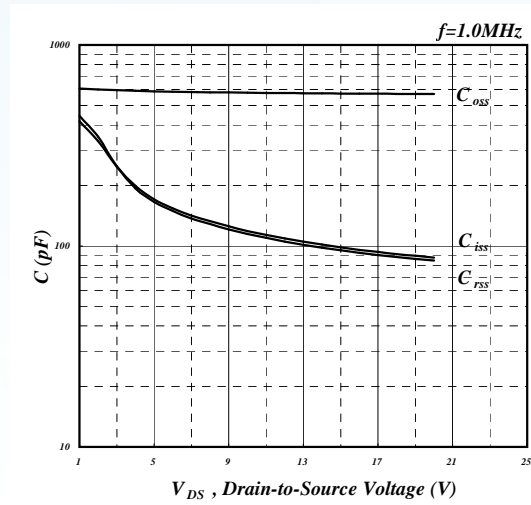


Fig 8. Typical Capacitance Characteristics

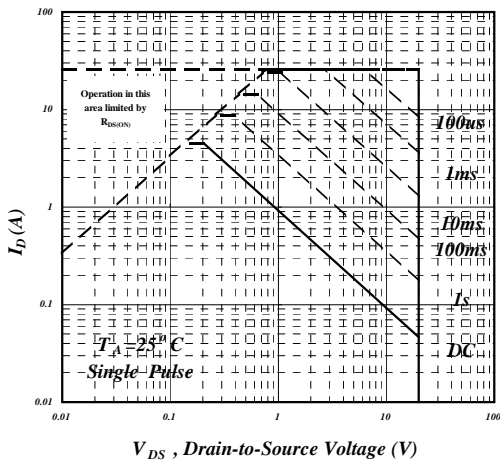


Fig 9. Maximum Safe Operating Area

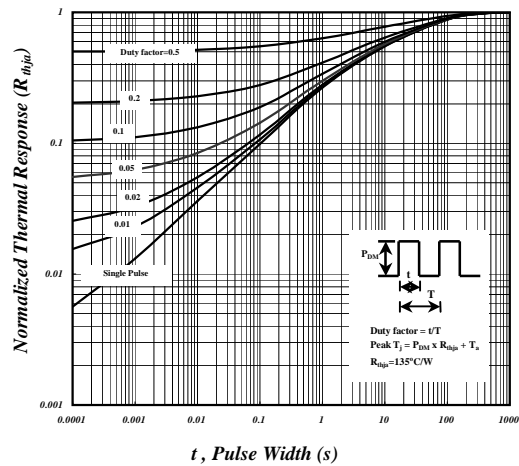


Fig 10. Effective Transient Thermal Impedance

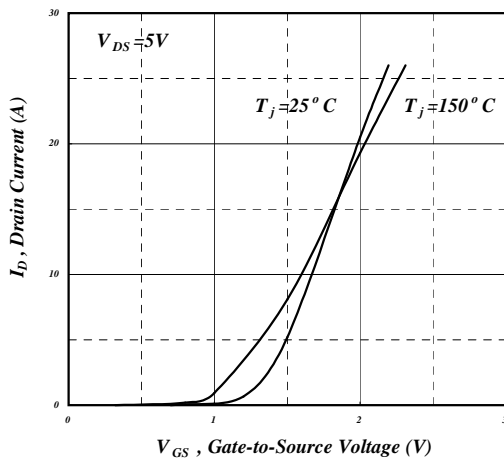


Fig 11. Transfer Characteristics

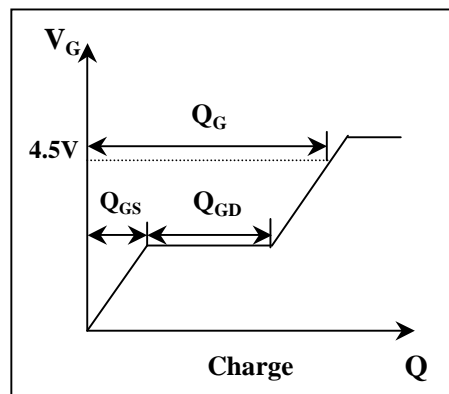
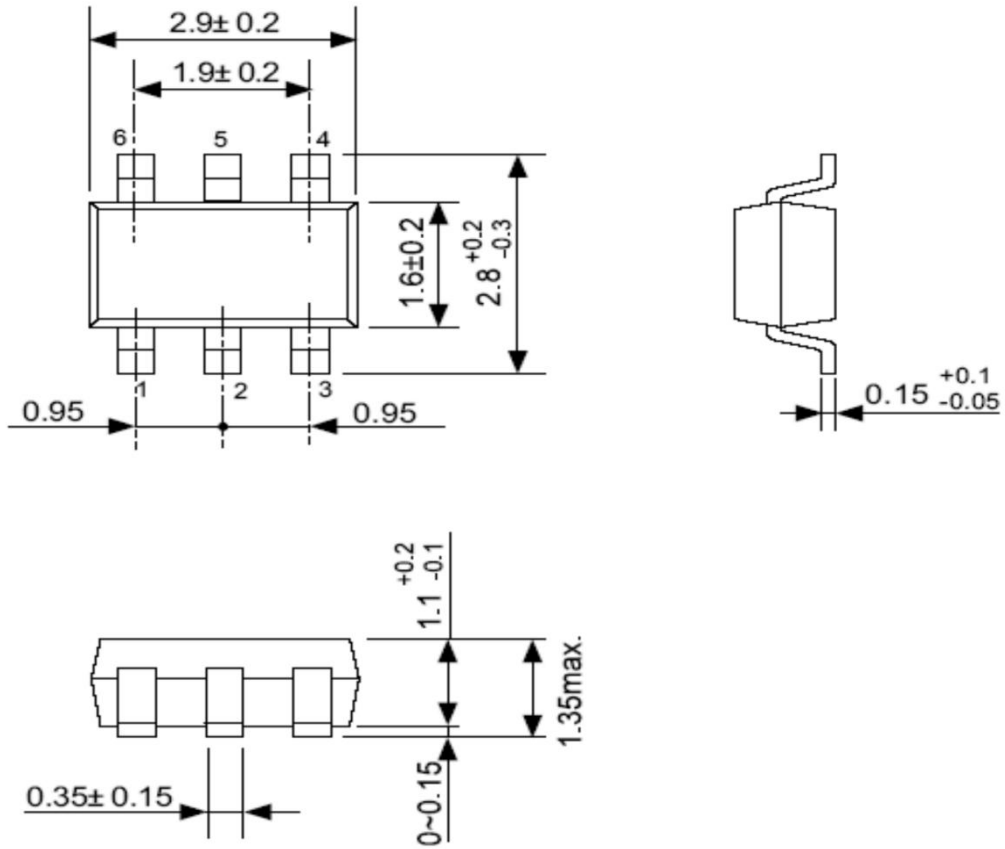


Fig 12. Gate Charge Waveform

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SOT23-6 PACKAGE INFORMATION



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